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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product StatusActiveCore ProcessorHCS12XCore Size16-BitSpeed50MHzConnectivityCANbus, EBI/EMI, PC, IrDA, SCI, SPIPeripheralsLVD, POR, PWM, WDTNumber of I/O91Program Memory Size512KB (512K x 8)Program Memory TypeFLASHEPROM Size4K x 8RAM Size32K x 8Voltage - Supply (Vcc/Vdd)1.72V ~ 5.5VData ConvertersA/D 16x12bOperating Temperature-40°C ~ 105°C (TA)Mounting TypeSurface MountPackage / Case112-LQFP (20x20)Purchase URLhttps://www.exfl.com/product-detail/nxp-semiconductors/sp12xeq512ftval		
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EEPROM Size4K x 8RAM Size32K x 8Voltage - Supply (Vcc/Vdd)1.72V ~ 5.5VData ConvertersA/D 16x12bOscillator TypeExternalOperating Temperature-40°C ~ 105°C (TA)Mounting TypeSurface MountPackage / Case112-LQFPSupplier Device Package112-LQFP (20x20)	Program Memory Size	512KB (512K x 8)
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Voltage - Supply (Vcc/Vdd)1.72V ~ 5.5VData ConvertersA/D 16x12bOscillator TypeExternalOperating Temperature-40°C ~ 105°C (TA)Mounting TypeSurface MountPackage / Case112-LQFPSupplier Device Package112-LQFP (20x20)	EEPROM Size	4K x 8
Data ConvertersA/D 16x12bOscillator TypeExternalOperating Temperature-40°C ~ 105°C (TA)Mounting TypeSurface MountPackage / Case112-LQFPSupplier Device Package112-LQFP (20x20)	RAM Size	32K x 8
Oscillator TypeExternalOperating Temperature-40°C ~ 105°C (TA)Mounting TypeSurface MountPackage / Case112-LQFPSupplier Device Package112-LQFP (20x20)	Voltage - Supply (Vcc/Vdd)	1.72V ~ 5.5V
Operating Temperature-40°C ~ 105°C (TA)Mounting TypeSurface MountPackage / Case112-LQFPSupplier Device Package112-LQFP (20x20)	Data Converters	A/D 16x12b
Mounting Type Surface Mount Package / Case 112-LQFP Supplier Device Package 112-LQFP (20x20)	Oscillator Type	External
Package / Case 112-LQFP Supplier Device Package 112-LQFP (20x20)	Operating Temperature	-40°C ~ 105°C (TA)
Supplier Device Package 112-LQFP (20x20)	Mounting Type	Surface Mount
	Package / Case	112-LQFP
Purchase URL https://www.e-xfl.com/product-detail/nxp-semiconductors/s912xeq512f1val	Supplier Device Package	112-LQFP (20x20)
	Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s912xeq512f1val

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MC9S12XE Family Product Brief 16-Bit Microcontroller Family with Enhanced System Integrity Features

1 Introduction

The new MC9S12XE Family of microcontrollers takes the innovation of today's MC9S12XD Family a step further with the introduction of new features to deliver enhanced system integrity and greater functionality. These new features include a Memory Protection Unit (MPU) and Error Correction Code (ECC) on the Flash memory together with enhanced EEPROM functionality (EEE), an enhanced XGATE, a Frequency Modulated Phase Locked Loop (IPLL) and a faster ATD. The E Family will extend the S12X product range up to 1MB of Flash memory with increased I/O capability in the 208-pin version of the flagship MC9S12XEP100.

Targeted at automotive multiplexing and generic auto body applications, S12XE Family will deliver 32-bit performance with all the advantages and efficiencies of a 16-bit MCU. It will retain the low cost, power consumption, EMC and codesize efficiency advantages currently enjoyed by users of Freescale's existing 16-bit S12 and S12X MCU families. There is a high level of compatibility between the S12XE and S12XD families.

Like members of other S12X families, the S12XE Family will run 16-bit wide accesses without wait states for all peripherals and memories.

The S12XE Family features an enhanced version of the performance-boosting XGATE co-processor which is programmable in "C" language and runs at twice the bus frequency of the S12X with an instruction set optimized for

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Application Examples

data movement, logic and bit manipulation instructions and which can service any peripheral module on the device. The new enhanced version has improved interrupt handling capability and is fully compatible with existing XGATE module.

As with the S12XD Family, the S12XE Family features an enhanced MSCAN module which, when used in conjunction with XGATE, delivers FULL CAN performance with virtually unlimited number of mailboxes and retains backwards compatibility with the MSCAN module featured on existing S12 products.

The S12XE Family has full 16-bit data paths throughout. The non-multiplexed expanded bus interface available on the 144pin versions allows an easy interface to external memories. In addition to the I/O ports available in each module, up to 25 further I/O ports are available with interrupt capability allowing wake-up from STOP or WAIT mode. The S12XE Family is available in 208-Pin MAPBGA, 144-pin LQFP (both with optional external bus), 112-pin LQFP or 80-Pin QFP options.

2 Application Examples

The following sections describe target applications of the MC9S12XE.

2.1 Body Controller Application Example

In this example, the MC9S12XE is implementing the features of a typical car body controller application. The module interfaces with the main CAN buses distributed in the car using the on-chip MSCAN module whereas the LIN bus communicates with functions local to the body controller. In both cases the communication functions are managed by the XGATE independently of the CPU. The MC9S12XE provides direct control of power drivers for lights and pumps and reading of sensors, using the on-chip PWM and ATD modules. Finally, the SPI interface to the RF receiver provides the interface to the car remote access system.

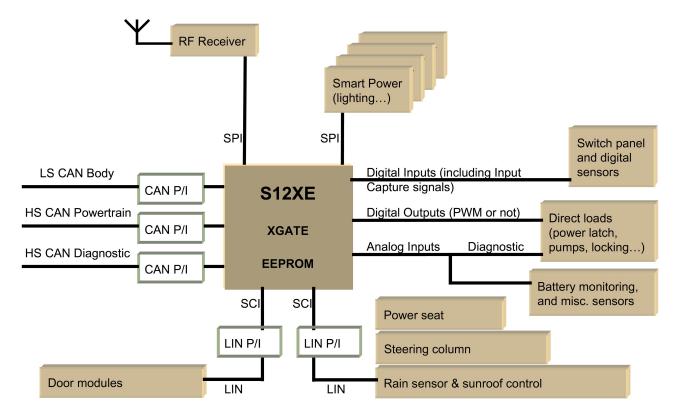


Figure 1. Body Controller Application Example



2.2 Gateway Application Example

In this application, the MC9S12XE provides gateway functionality between its on-chip CAN and LIN modules. Much of the low-level communications functionality is handled by the XGATE, which frees the CPU to manage higher level communications and other direct connections to the module.

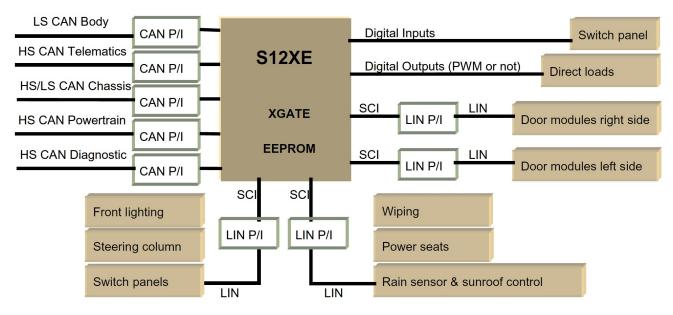


Figure 2. Gateway Application Example

3 Features

Features of the S12XE Family are described in this section.

3.1 Block Diagram

Figure 3 shows a top-level block diagram of the S12XE Family.



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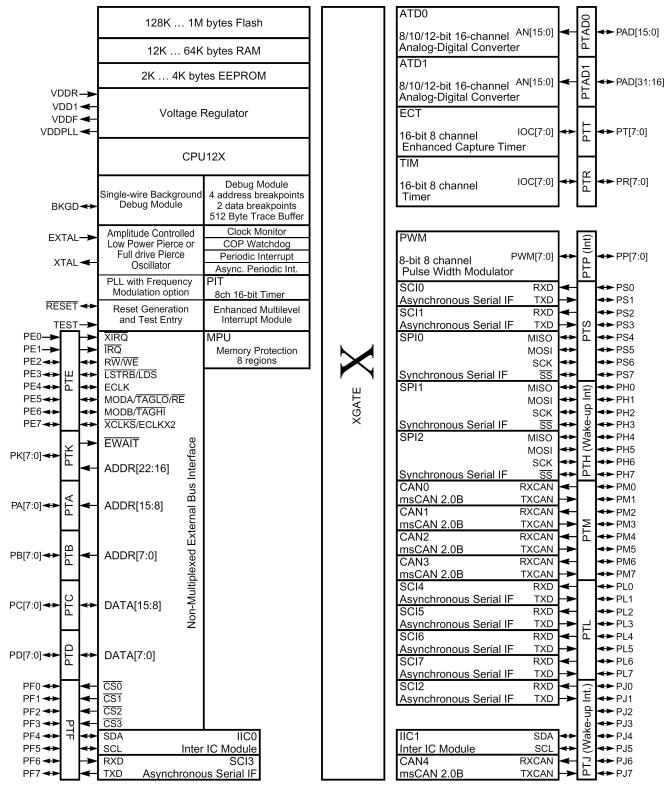


Figure 3. MC9S12XE Block Diagram



3.2 Peripheral and Memory Options S12XE Family

Table 1. Peripheral and Memory Options of S12XE Family Members

Device	Package	XGA TE	CAN ¹	SCI ²	SPI ³	IIC ⁴	ECT	TIM ⁵	PIT	A/D ⁶	I/O ^{7, 8}	Flash	RAM	EEPRO M (D- Flash)
9S12XEP 100	208 MAPBGA	Yes	5	8	3	2	8ch	8ch	8ch	2/32	152	1M	64K	4K (32K)
	144LQFP		5	8	3	2	8ch	8ch	8ch	2/24	119			
	112LQFP		5	8	3	1	8ch	8ch	8ch	2/16	91			
	80QFP		4	2	3	1	8ch	8ch	8ch	1/8	59			
9S12XEP 768	208 MAPBGA		5	8	3	2	8ch	8ch	8ch	2/32	152	768K	48K	
	144LQFP		5	8	3	2	8ch	8ch	8ch	2/24	119	59 19 512K 32	32K	32K
	112LQFP		5	8	3	1	8ch	8ch	8ch	2/16	91			
	80QFP		4	2	3	1	8ch	8ch	8ch	1/8	59			
9S12XEQ	144LQFP		4	6	3	2	8ch	0	4ch	2/24	119			
512	112LQFP		4	6	3	1	8ch	0	4ch	1/16	91			
	80QFP		4	2	3	1	8ch	0	4ch	1/8	59			
9S12XEQ	144LQFP		4	6	3	2	8ch	0	4ch	2/24	119	384K	24K	
384	112LQFP		4	6	3	1	8ch	0	4ch	2/16	91			
	80QFP		4	2	3	1	8ch	0	4ch	1/8	59			
9S12XET 256	144LQFP		3	4	3	1	8ch	0	4ch	2/24	119	256K	16K	
	112LQFP		3	4	3	1	8ch	0	4ch	2/16	91			
	80QFP		3	2	3	1	8ch	0	4ch	1/8	59			
9S12XEG 128	112LQFP	Yes ⁹	2	2	2	1	8ch	0	2ch	2/16	91	128K	12K	2K (32K)
	80QFP		2	2	2	1	8ch	0	2ch	1/8	59			

1. CAN Options:

Versions with 5 CAN modules will have CAN0, CAN1, CAN2, CAN3 and CAN4.

Versions with 4 CAN modules will have CAN0, CAN1, CAN2 and CAN4.

Versions with 3 CAN modules will have CAN0, CAN1 and CAN4.

Versions with 2 CAN modules will have CAN0 and CAN4.

Versions with 1 CAN module will have CAN0.

2. SCI Options:

Versions with 8 SCI modules will have SCI0, SCI1, SCI2, SCI3, SCI4, SCI5, SCI6 and SCI7.

Versions with 7 SCI modules will have SCI0, SCI1, SCI2, SCI3, SCI4, SCI5, and SCI6.

Versions with 6 SCI modules will have SCI0, SCI1, SCI2, SCI3, SCI4 and SCI5.

Versions with 5 SCI modules will have SCI0, SCI1, SCI2, SCI3 and SCI4.

Versions with 4 SCI modules will have SCI0, SCI1, SCI2 and SCI4.

Versions with 3 SCI modules will have SCI0, SCI1 and SCI2.

Versions with 2 SCI modules will have SCI0 and SCI1.

Versions with 1 SCI module will have SCI0.

3. SPI Options:



Versions with 3 SPI modules will have SPI0, SPI1 and SPI2.

Versions with 2 SPI modules will have SPI0 and SPI1.

Versions with 1 SPI modules will have SPI0.

4. IIC Options:

Versions with 2 IIC modules will have IIC0 and IIC1.

Versions with 1 IIC module will have IICO.

- 5. TIM available via rerouting on EP100,EP768 devices 80/112/144 pinout options
- 6. A/D is the number of modules/total number of A/D channels.
- I/O is the sum of ports capable to act as digital input or output. For details see the "Port Availability by Package Option" table in the MCS12XE Data Sheet.
- I/O is the sum of ports capable to act as digital input or output. For details see the "Port Availability by Package Option" table in the MCS12XE Data Sheet.
- 9. Can only execute code from RAM

3.3 Critical Performance Parameters

The following describes the critical operating parameters of the MCU.

3.3.1 Operating Conditions

- Wide single supply voltage range 3.3V-5%/+10% to 5.0V+10% at full performance
 - · Separate supply for internal voltage regulator and I/O allow optimized EMC filtering
 - 50MHz maximum CPU bus frequency
 - 100MHz maximum XGATE bus frequency
- Ambient temperature range -40°C to 125°C
- Temperature Options:
 - -40°C to 85°C
 - -40°C to 105°C
 - -40°C to 125°C

3.3.2 Package Options

- 208-pin MAPBGA 17mm x 17mm body size (case no 1159A-01 issueB)
- 144-pin low-profile quad flat-pack (LQFP) 20x20mm body size, 0.5mm pitch (case no 918-03)
- 112-pin low-profile quad flat-pack (LQFP) 20x20mm, 0.65 pitch (case no 987)
- 80-pin quad flat-pack (QFP)- 14x14mm body, 0.65mm pitch (case no 841B)

3.4 Chip-Level Features

On-chip modules include the following features:

- Pin compatible family extends existing S12D Family
- 16-bit CPU12X
- Enables higher system integrity at the MCU level (MPU, ECC, Supervisor Mode)
- Enhanced SPI allows 8 or 16 bit data size
- ECC on flash





- 1-bit fault correction
- 2-bit fault detection
- Improved EMC performance
 - Separate supply for internal voltage regulator and I/O allow optimized EMC filtering
- Enhanced current consumption
- Extended API up to 5 sec

3.5 Module Features

The following sections provide more details of the modules implemented on the MC9S12XE.

3.5.1 16-Bit CPU12X

- 16-bit CPU12X
- Compatible with MC9S12 instruction set with the exception of five fuzzy instructions (MEM, WAV, WAVR, REV, REVW) which have been removed.
- Enhanced indexed addressing
- · Access to large data segments independent of PPAGE

3.5.2 Enhanced Interrupt Module

- Eight levels of nested interrupts
- Flexible assignment of interrupt sources to each interrupt level.
- External non-maskable high priority interrupt (XIRQ)
- Internal, non-maskable high priority memory protection unit interrupt
- Up to 24 pins on ports J, H and P configurable as rising or falling edge sensitive

3.5.3 XGATE

- Programmable, high performance I/O coprocessor module with up to 100 MIPS RISC performance
- Transfers data to or from all peripherals and RAM without CPU intervention or CPU wait states
- Performs logical, shifts, arithmetic, and bit operations on data
- Can interrupt the S12X CPU signalling transfer completion
- Triggers from any hardware module as well as from the CPU possible
- Two interrupt levels to service high priority tasks
- · Enables Full CAN capability when used in conjunction with MSCAN module
- Full LIN master or slave capability when used in conjunction with the integrated LIN SCI modules

3.5.4 Memory Protection Unit (MPU)

- 8 address regions definable per active program task
- Address range granularity as low as 8-bytes
- Protection Attributes
 - No write
 - No execute



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· Non-maskable interrupt on access violation

3.5.5 System Integrity Support

- Power-on reset (POR)
- Illegal address detection with reset
- Low-voltage detection with interrupt or reset
- System can run in Supervisor or User state
 - using a new bit in the condition code register
 - peripheral space can only be accessed in user state if enabled by a descriptor
- Computer Operating Properly (COP) watchdog
 - Configurable as window COP for enhanced failure detection
 - Can be initialized out of reset using option bits located in Flash
- Clock monitor supervising the correct function of the oscillator

3.5.6 Memory Options

- 128K, 256K, 384K, 512K, 768K and 1M byte Flash
- 2K, 4K byte Emulated EEPROM
- 12K, 16K, 24K, 32K, 48K and 64K Byte RAM
- Flash General Features
 - 64 data bits plus 8 syndrome ECC (Error Correction Code) bits allow single bit failure correction and double fault detection
 - Erase sector size 1024 bytes
 - Automated program and erase algorithm
 - Security option to prevent unauthorized access
 - Sense-amp margin level setting for reads
- Data Flash General Features
 - 32 Kbytes of D-Flash memory with 256-byte sectors for user access.
 - · Dedicated commands to access D-Flash memory over EEE operation
 - Single bit fault correction and double fault detection within a word during read operations
 - · Automated program and erase algorithm with verify and generation of ECC parity bits
 - · Fast sector erase and word program operation
 - Ability to program up to four words in a burst sequence
- Emulated EEPROM General Features
 - Automatic EEE file handling using internal Memory Controller
 - Automatic transfer of valid EEE data from D-Flash memory to buffer RAM on reset
 - Ability to monitor the number of outstanding EEE related buffer RAM words left to be programmed into D-Flash memory
 - Ability to disable EEE operation and allow priority access to the D-Flash memory
 - · Ability to cancel all pending EEE operations to allow priority access to the D-Flash memory

3.5.7 Oscillator (OSC_LCP)

- Loop Control Pierce oscillator utilizing a 4MHz to 16MHz crystal
- Good noise immunity



- Full-swing Pierce option utilizing a 2MHz to 40MHz crystal
- Transconductance sized for optimum start-up margin for typical crystals

3.5.8 Clock and Reset Generator (CRG)

- Phase-locked-loop (IPLL) clock frequency multiplier
 - Internally filtered. No external components required
 - Configurable option to spread spectrum for reduced EMC radiation (frequency modulation)
- · Fast wake up from STOP in self clock mode for power saving and immediate program execution

3.5.9 Non-Multiplexed External Bus (208-pin and 144-pin packages only)

- Non-Multiplexed External Bus (208-pin and 144-pin packages only)
 - Each chip select output can be configured to complete transaction on either the time-out of one of the two wait state generators or the deassertion of EWAIT signal
- · Supports glue-less interface to popular asynchronous RAMs and Flash devices

3.5.10 Analog-to-Digital Converter (ATD)

- Up to two independent ATD converters
- 8/10/12 bit resolution
- Multiplexer for 16 analog input channels
- 3 s, 10-bit single conversion time
- Left/right, signed/unsigned result data
- External and internal conversion trigger capability
- Internal oscillator for conversion in Stop modes
- Wake-up from low power modes on analog comparison > or <= match

3.5.11 Enhanced Capture Timer (ECT)

- 8 x 16-bit channels for input capture or output compare
- 16-bit free-running counter with 8-bit precision prescaler
- 16-bit modulus down counter with 8-bit precision prescaler
- Four 8-bit or two 16-bit pulse accumulators
- Four channels have enhanced input capture capabilities:
 - Delay counter for noise immunity
 - 16-bit capture buffer
 - 8-bit pulse accumulator buffer

3.5.12 Timer (TIM)

- 8 x 16-bit channels for input capture or output compare
- 16-bit free-running counter with 8-bit precision prescaler
- One 16-bit pulse accumulator



3.5.13 Periodic Interrupt Timer (PIT)

- Up to 8 timers with independent time-out periods
- Time-out periods selectable between 1 and 224 bus clock cycles
- · Time-out interrupt and peripheral triggers

3.5.14 Real Time Interrupt (RTI)

- · Real time interrupt for task scheduling purposes or cyclic wake-up
- Can be active in Pseudo Stop mode for low power precision timing tasks

3.5.15 Asynchronous Periodic Interrupt (API)

- Available in all modes including Full Stop mode
- Trimmable to +-10% accuracy
- Time-out periods range from 0.2ms to ~13s with a 0.2ms resolution

3.5.16 Pulse Width Modulator (PWM)

- 8 channel x 8-bit or 4 channel x 16-bit Pulse Width Modulator
- Programmable period and duty cycle per channel
- Center- or left-aligned outputs
- · Programmable clock select logic with a wide range of frequencies
- · Fast emergency shutdown input

3.5.17 Multi-scalable Controller Area Networks (MSCAN)

- Up to five MSCAN modules
- CAN 2.0 A, B software compatible
 - Standard and extended data frames
 - 0 8 bytes data length
 - Programmable bit rate up to 1 Mbps
- Five receive buffers with FIFO storage scheme
- Three transmit buffers with internal prioritization
- Flexible identifier acceptance filter programmable as:
 - 2 x 32-bit
 - 4 x 16-bit
 - 8 x 8-bit
- · Wake-up with integrated low pass filter option
- Loop back for self test
- Listen-only mode to monitor CAN bus
- · Bus-off recovery by software intervention or automatically
- 16-bit time stamp of transmitted/received messages
- FULL-CAN capability when used in conjunction with XGATE





3.5.18 Serial Peripheral Interface (SPI)

- Up to three SPI modules
- Configurable 8 or 16-bit data size
- Full-duplex or single-wire bidirectional
- Double-buffered transmit and receive
- Master or Slave mode
- MSB-first or LSB-first shifting
- · Serial clock phase and polarity options

3.5.19 Serial Communication Interfaces (SCI)

- Up to eight SCI modules
- Full-duplex or single wire operation
- Standard mark/space non-return-to-zero (NRZ) format
- Selectable IrDA 1.4 return-to-zero-inverted (RZI) format with programmable pulse widths
- 13-bit baud rate selection
- Programmable character length
- Programmable polarity for transmitter and receiver
- · Receive wake-up on active edge
- · Break detect and transmit collision detect supporting LIN

3.5.20 Inter-IC Module (IIC)

- Up to two IIC modules
- Compatible with Inter-IC Bus standard
- Multi-master operation
- Software programmable for one of 256 different serial clock frequencies
- · Broadcast mode support
- 10-bit address support

3.5.21 Background Debug (BDM)

- Background debug module (BDM) with single-wire interface
 - Non-intrusive memory access commands
 - · Supports in-circuit programming of on-chip non-volatile memory
 - Supports security

3.5.22 Debugger (xDBG)

- Four comparators A, B, C and D
 - Each can monitor CPU or XGATE buses
 - A and C compares 23-bit address bus and 16-bit data bus with mask register
 - B and D compares 23-bit address bus only
 - Three comparator modes: exact address match, inside address range or outside address range



Jeveloper Environment

- 64 x 64-bit circular trace buffer to capture change-of-flow addresses or address and data of every access
- Tag-type or force-type hardware breakpoint requests

3.5.23 On-Chip Voltage Regulator (VREG)

- Two parallel, linear voltage regulators with bandgap reference
- Low-voltage detect (LVD) with low-voltage interrupt (LVI)
- Power-on reset (POR) circuit
- 3V and 5V range operation
- Low-voltage reset (LVR)

3.5.24 Input/Output

- Up to 152 general-purpose input/output (I/O) pins and 2 input-only pins
- Hysteresis and configurable pull up/pull down device on all input pins
- · Configurable drive strength on all output pins

4 Developer Environment

The S12XE Family of MCUs supports similar tools and third party developers as other Freescale S12X products, offering a widespread, established network of tools and software vendors. Available support includes:

S12X Evaluation Board

- Full standardized header ring for all pins (except Oscillator and PLL)
- 6 LIN Interfaces
- 2 RS232(2) Interfaces
- 3 CAN Interfaces
- Power Supply Connector
- Prototyping area
- USB, BDM and USB2BDM interface
- Daughter boards with 144, 112, and 80 pin devices
- Canned Oscillator
- · Pierce Oscillator provision
- Reverse polarity protection
- Configuration jumpers (mode pins, clock source, vreg)
- 0 Ohm resistor going from test to ground
- Ground points
- Kit includes:
 - USB cable
 - CodeWarrior CD
 - 9S12XDP512 Service Pack CD
 - EVB9S12X Evaluation Board User Manual
 - SofTec System Software CD
 - Status: Available Now!

MC9S12 Code Warrior Development System -> S12X "Service Pack" contains:

- CodeWarrior for OSEK
- Sophisticated project manager
 - Build system with optimizing C/C++ compiler
 - Graphical, source-level debugger



- Fast, cycle-accurate simulator
- Code coverage and profile analysis
- Flash programmer
- Evaluation Kit for MC9S12DT256
 - Evaluation board
 - BDI interface
 - Power supplies and cables
- Metrowerks OSEK Real-Time Operating System (demo)
- Documentation package

Name / Tool	IDE/Compiler	Debugger	Simulator	Emulator	BDM Conn.	
		Soft	ware			
CodeWarrior	X	Х	Х			
Cosmic Software	Х	Х	Х			
IAR Systems	Х	Х	X			
	I	Hard	lware			
P&E Microcomputer Systems, Inc.					X	
iSystem	Х	Х		Х	X	
Nohau		Х		Х		
Lauterbach		Х		Х	X	
	I	Driv	vers			
Vector LIN 1.3 Master Driver S12X. LIN 2.0 Master Driver S12X (including XGATE) • CAN Driver S12X (including XGATE). This includes COM and NM for specific OEM configuration						
3Soft	I/O (HIS) Drivers + LIN 2.0 Master and Slave Drivers ProOSEK for S12X					
Volcano	LIN Drivers For S12 available and compatible for S12X					

Table 2. Tools Suppliers

5 Document Revision History

Table 3 shows the revision history of this document.

Revision	Location(s)	Substantive Change(s)
Rev. 2		Replaced high-level block diagram with detailed block diagram.
		Added Table 1.
		Added Table 2.
Rev. 3		Replaced future tense with present tense
		Corrected corrupted footnote font in Table 1.
		Added dataflash column to Table 2.
		Changed CPU compatibility text following removal of fuzzy instructions

Table continues on the next page ...



Document Revision History

Revision	Location(s)	Substantive Change(s)			
Rev. 4		Merged device family option tables			
Rev. 5		Added package mechanical information			
Rev. 6		Changed D-Flash size for S12XEG128			
Rev. 7		Corrected SCI,IIC,PIT counts in derivative table			
Rev. 8		Table 1. updated TIM listing, added 80QFP options.			

Table 3. Revision History (continued)



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